

## RF Amplifier for CD Player/CD-ROM

### Description

The CXA2557R is an RF signal processing IC for CD players, CD-ROM and CD-RW (playback).

### Features

- Wide-band RF AC amplifier
- Supports CD-RW playback (RF DC, RF AC, FE, TE and AL amplifiers)
- 5-mode RF AC equalizer (active filter type)
- RF AC equalizer boost amount and cut-off frequency adjustable
- Voltage gain adjustable for RF DC, RF AC, FE, TE and AL amplifier
- RF DC amplifier offset voltage switchable
- FE and TE amplifier bias voltage adjustable
- Tracking error amplifier cut-off frequency adjustable
- Alignment amplifier
- Center error amplifier
- AGC (Automatic Gain Control) function
- APC (Automatic Power Control) function
- VC/VC IN separation
- Supports laser coupler/3 spots

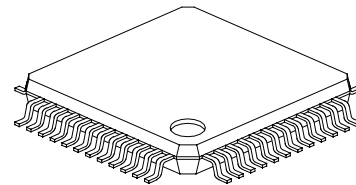
### Functions

- RF DC summing amplifier
- RF AC summing amplifier
- RF AC equalizer
- Focus error (FE) amplifier
- Tracking error (TE) amplifier
- Alignment (AL) amplifier
- Center error (CE) amplifier
- Mirror circuit
- AGC circuit
- VREF output

### Applications

- CD players
- CD-ROM drives

48 pin LQFP (Plastic)



### Structure

Bipolar silicon monolithic IC

### Absolute Maximum Ratings (Ta = 25°C)

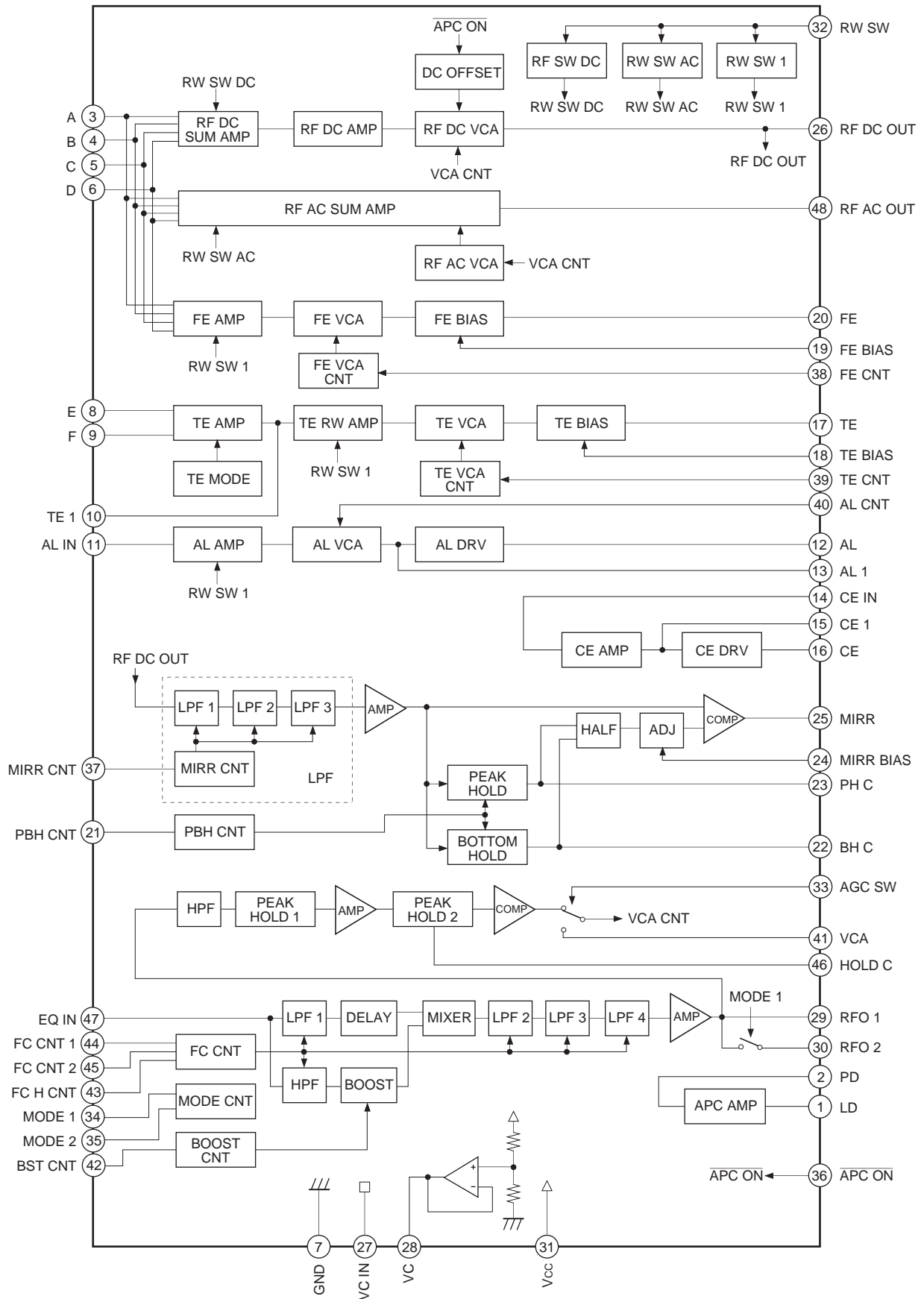
- |                       |                       |             |    |
|-----------------------|-----------------------|-------------|----|
| • Supply voltage      | V <sub>CC</sub> – GND | 7           | V  |
| • Storage temperature | T <sub>stg</sub>      | –65 to +150 | °C |
| • Power consumption   | P <sub>D</sub>        | 400         | mW |

### Operating Conditions (Ta = 25°C)

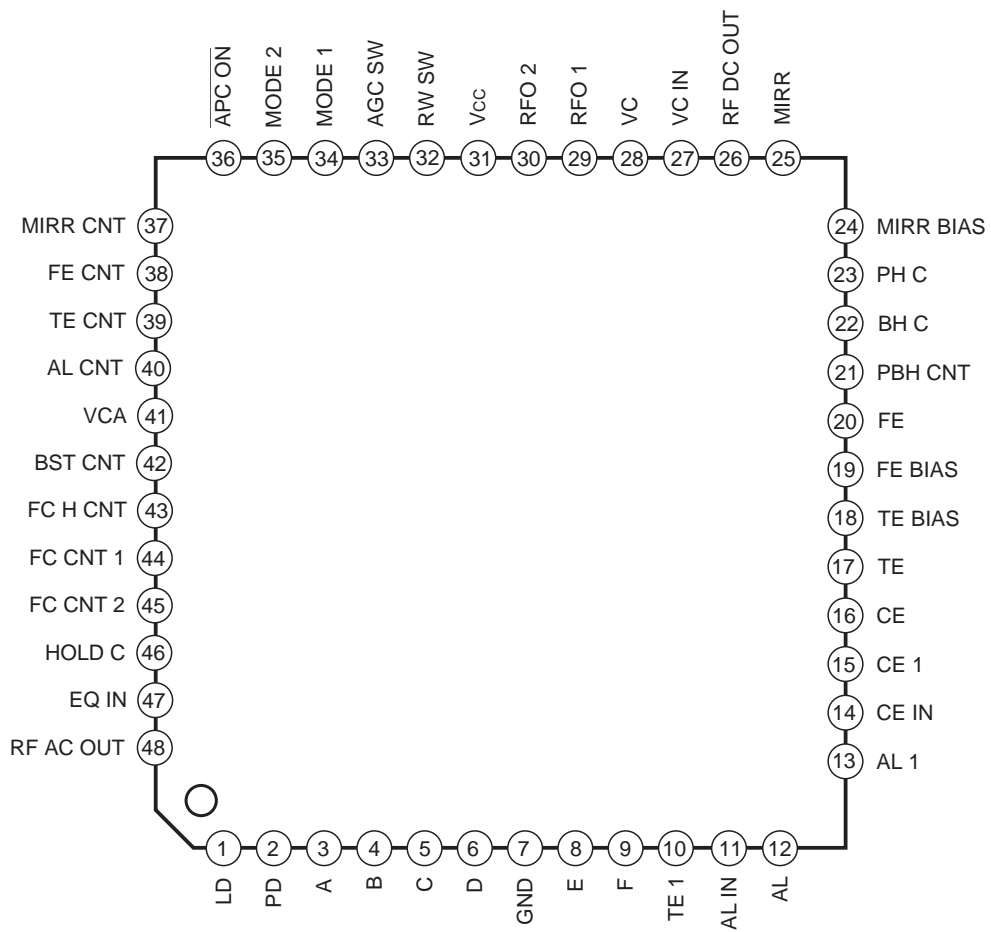
- |                         |                       |            |    |
|-------------------------|-----------------------|------------|----|
| • Supply voltage        | V <sub>CC</sub> – GND | 3.5 to 5.5 | V  |
| • Operating temperature | T <sub>opr</sub>      | –20 to +75 | °C |

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Block Diagram



Pin Configuration



Pin Description

Pin No.	Symbol	I/O	Equivalent circuit	Description
1	LD	O		APC amplifier output.
2	PD	I		APC amplifier input.
3 4 5 6	A B C D	I I I I		Inputs of RF summing amplifier and focus error amplifier. When using a laser coupler: A + C = PD1 B + D = PD2
7	GND		—	Ground.

Pin No.	Symbol	I/O	Equivalent circuit	Description
8 9	E F	I I		Tracking error amplifier inputs.
10	TE 1	O		Tracking error amplifier inverted output.
11	AL IN	I		Alignment amplifier input.
12	AL	O		Alignment amplifier non-inverted output.
13	AL 1	O		Alignment amplifier inverted output.
14	CE IN	I		Center error amplifier input.
15	CE 1	O		Center error amplifier inverted output.
16	CE	O		Center error drive amplifier inverted output.

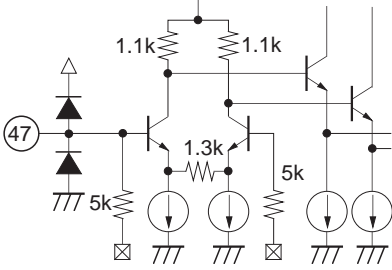
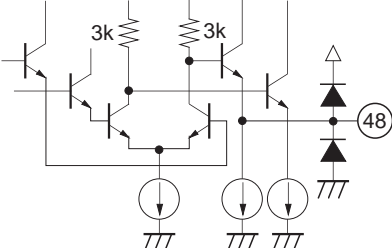
Pin No.	Symbol	I/O	Equivalent circuit	Description
17	TE	O		Tracking error amplifier non-inverted output.
18	TE BIAS	I		Tracking error amplifier bias adjustment.
19	FE BIAS	I		Focus error amplifier bias adjustment.
20	FE	O		Focus error amplifier non-inverted output.
21	PBH CNT	I		Mirror circuit peak hold and bottom hold time constant setting input.
22	BC C	I		Connects the capacitor that sets mirror circuit bottom hold time constant.
23	PH C	I		Connects the capacitor that sets mirror circuit peak hold time constant.
24	MIRR BIAS	I		Mirror circuit bias adjustment.

Pin No.	Symbol	I/O	Equivalent circuit	Description
25	MIRR	O		Mirror comparator output.
26	RF DC OUT	O		RF DC amplifier output. Eye pattern check point.
27	VC IN	I	—	Reference voltage input.
28	VC	O		$(V_{CC} + GND)/2$ voltage output.
29	RFO 1	O		RF AC amplifier output.
30	RFO 2	O		RF AC amplifier buffer switch output. ON when Pin 34 is connected to GND.
31	V <sub>CC</sub>	—	—	Power supply.

Pin No.	Symbol	I/O	Equivalent circuit	Description																
32	RW SW	I		CD-ROM/RW switching input. RW when connected to V <sub>CC</sub> , ROM when connected to GND.																
33	AGC SW	I		AGC/VCA switching input. AGC when connected to V <sub>CC</sub> , VCA when connected to GND.																
34	MODE 1	I		<p>Double-speed mode switching pins.</p> <table border="1"> <thead> <tr> <th>MODE 1</th> <th>MODE 2</th> <th>f<sub>c</sub></th> </tr> </thead> <tbody> <tr> <td>L</td> <td>X</td> <td>× n</td> </tr> <tr> <td rowspan="2">M</td> <td>L</td> <td>× 2n</td> </tr> <tr> <td>M</td> <td>× 4n</td> </tr> <tr> <td rowspan="2">H</td> <td>H</td> <td>× 6n</td> </tr> <tr> <td>X</td> <td>× N</td> </tr> </tbody> </table> <p>* X = L or M or H n is determined by the external resistor connected to Pin 44. N is determined by the external resistor connected to Pin 45 and the Pin 43 input voltage.</p> <p>Pin 34 also serves as switching pin for the tracking error amplifier cut-off frequency and RFO2 output ON/OFF switching pin.</p>	MODE 1	MODE 2	f <sub>c</sub>	L	X	× n	M	L	× 2n	M	× 4n	H	H	× 6n	X	× N
MODE 1	MODE 2	f <sub>c</sub>																		
L	X	× n																		
M	L	× 2n																		
	M	× 4n																		
H	H	× 6n																		
	X	× N																		
35	MODE 2	I		<table border="1"> <thead> <tr> <th>MODE 1</th> <th>MODE 2</th> <th>f<sub>c</sub></th> </tr> </thead> <tbody> <tr> <td>L</td> <td>20kHz</td> <td>ON</td> </tr> <tr> <td>M</td> <td rowspan="2">250kHz</td> <td rowspan="2">OFF</td> </tr> <tr> <td>H</td> </tr> </tbody> </table> <p>* L = GND, M = VC, H = V<sub>CC</sub></p>	MODE 1	MODE 2	f <sub>c</sub>	L	20kHz	ON	M	250kHz	OFF	H						
MODE 1	MODE 2	f <sub>c</sub>																		
L	20kHz	ON																		
M	250kHz	OFF																		
H																				

Pin No.	Symbol	I/O	Equivalent circuit	Description
36	APC ON	I		<p>Switching pin for RF DC amplifier offset setting.                      No addition to RF DC amplifier when Medium (VC).                      Vcc/6 added to RF DC amplifier when Low (GND).</p>
37	MIRR CNT	I		<p>Mirror circuit LPF cut-off frequency setting input.</p>
38	FE CNT	I		<p>Focus error amplifier gain adjustment input.</p>
39	TE CNT	I		<p>Tracking error amplifier gain adjustment input.</p>
40	AL CNT	I		<p>Alignment amplifier gain adjustment input.</p>

Pin No.	Symbol	I/O	Equivalent circuit	Description
41	VCA	I		RF DC and RF AC amplifier gain adjustment input. AGC circuit target voltage input when AGC SW is ON.
42	BST CNT	I		Equalizer circuit boost amount adjustment input.
43	FC H CNT	I		Cut-off frequency N adjustment input when Pin 34 is High.
44	FC CNT 1	I		Connects the external resistor that sets cut-off frequency n when Pin 34 is Low or Medium.
45	FE CNT 2	I		Connects the external resistor that sets cut-off frequency N when Pin 34 is High.
46	HOLD C	I		Connects the capacitor that sets AGC time constant.

Pin No.	Symbol	I/O	Equivalent circuit	Description
47	EQ IN	I		Equalizer circuit input.
48	RF AC OUT	O		RF AC summing amplifier non-inverted output.

(Ta = 25°C, Vcc = 1.9V, GND = VC, VEE = -1.9V)

Electrical Characteristics

No.	Measurement item	SW conditions	Bias conditions (V)		Input	Output *IC pin No.	Ratings			
			E1	E2			Min.	Typ.	Max.	Unit
1	Output voltage	VVCB				28	-20.0	0.0	20.0	mA
2	Current consumption	ICC				31	43.0	64.0	85.0	mA
3	Current consumption	IEE				7	-85.0	-64.0	-43.0	mA
4	Output offset voltage 1	VRFD1				26	-680.0	-560.0	-440.0	mV
5	Output offset voltage 2	VRFD2	S16				-640.0	-520.0	-400.0	mV
6	Output offset voltage 3	VRFD3	S20-b				-68.0	52.0	172.0	mV
7	Output offset voltage 1	VRFA1				48	-215.0	-135.0	-55.0	mV
8	Output offset voltage 2	VRFA2	S16				-210.0	-130.0	-50.0	mV
9	Output offset voltage 1	VFE1				20	-57.0	23.0	103.0	mV
10	Output offset voltage 2	VFE2	S16				-60.0	20.0	100.0	mV
11	Output offset voltage 1	VTE1				17	-210.0	-80.0	50.0	mV
12	Output offset voltage 2	VTE2	S16				-210.0	-80.0	50.0	mV
13	Output offset voltage 1	VAL1				12	-10.0	50.0	110.0	mV
14	Output offset voltage 2	VAL2	S16				-10.0	50.0	110.0	mV
15	Output offset voltage 3	VAL3				13	-110.0	-50.0	10.0	mV
16	Output offset voltage 4	VAL4	S16				-110.0	-50.0	10.0	mV
17	Output offset voltage	VCE				16	-30.0	20.0	70.0	mV
18	Voltage gain 1	GRFD1	S2, S3, S4, S5		100kHz 80mVp-p	26	13.8	16.8	19.8	dB
19	VCA gain 1	GRFDV1	S2, S3, S4, S5, S25	1.0			5.0	8.0	11.0	dB
20	VCA gain 2	GRFDV2	S2, S3, S4, S5, S25	-1.0			-11.0	-8.0	-5.0	dB
21	Voltage gain 2	GRFD2	S2, S3, S4, S5, S16		100kHz 18mVp-p		10.0	13.0	16.0	dB
22	VCA gain 3	GRFDV3	S2, S3, S4, S5, S16, S25	1.0			5.0	8.0	11.0	dB
23	VCA gain 4	GRFDV4	S2, S3, S4, S5, S16, S25	-1.0			-11.0	-8.0	-5.0	dB

(Ta = 25°C, VCC = 1.9V, GND = VC, VEE = -1.9V)

No.	Measurement item	SW conditions	Bias conditions (V)		Input	Output *IC pin No.	Ratings			
			E1	E2			Min.	Typ.	Max.	Unit
24	Output voltage High	S2, S3, S4, S5			1.0V DC	26	990.0	1100.0	—	mV
25	Output voltage Low	S2, S3, S4, S5			-1.0V DC	▶	—	-1790.0	-1680.0	mV
26	Voltage gain 1	S2, S3, S4, S5			100kHz 170mVp-p	48	0.7	2.7	4.7	dB
27	VCA gain 1	S2, S3, S4, S5, S25		1.0				8.0	10.0	dB
28	VCA gain 2	S2, S3, S4, S5, S25		-1.0	▶			-8.0	-6.0	dB
29	Voltage gain 2	S2, S3, S4, S5, S16			100kHz 38mVp-p		8.1	10.1	12.1	dB
30	VCA gain 3	S2, S3, S4, S5, S16, S25		1.0			5.5	7.5	9.5	dB
31	VCA gain 4	S2, S3, S4, S5, S16, S25		-1.0	▶		-9.5	-7.5	-5.5	dB
32	Output voltage High	S2, S3, S4, S5			1.0V DC		260.0	370.0	480.0	mV
33	Output voltage Low	S2, S3, S4, S5			-1.0V DC	▶	-730.0	-620.0	-510.0	mV
34	Voltage gain 1	S2, S4			1kHz 189mVp-p	20	13.0	16.0	19.0	dB
35	Voltage gain 2	S3, S5					13.0	16.0	19.0	dB
36	VCA gain 1	S3, S5, S22		1.0			5.0	8.0	11.0	dB
37	VCA gain 2	S3, S5, S22		-1.0	▶		-11.0	-8.0	-5.0	dB
38	Frequency response	S3, S5			25kHz 189mVp-p		-3.0	—	—	dB
39	Voltage gain 3	S2, S4, S16			1kHz 42mVp-p		10.0	13.0	16.0	dB
40	Voltage gain 4	S3, S5, S16					10.0	13.0	16.0	dB
41	VCA gain 3	S3, S5, S16, S22		1.0			5.0	8.0	11.0	dB
42	VCA gain 4	S3, S5, S16, S22		-1.0	▶		-11.0	-8.0	-5.0	dB
43	Bias characteristics 1	S11	1.0				-1290.0	-1180.0	-1070.0	mV
44	Bias characteristics 2	S11	-1.0				1070.0	1180.0	1290.0	mV
45	Output voltage High	S3, S5			1.9V DC		1660.0	1770.0	—	mV
46	Output voltage Low	S3, S5			-1.9V DC	▶	—	-1680.0	-1570.0	mV

(Ta = 25°C, Vcc = 1.9V, GND = VC, VEE = -1.9V)

No.	Measurement item	SW conditions	Bias conditions (V)		Input	Output *IC pin No.	Ratings			
			E1	E2			Min.	Typ.	Max.	Unit
47	Voltage gain 1	S7, S18-c			1kHz 107mVp-p	17	17.9	20.9	23.9	dB
48	Voltage gain 2	S6, S18-c					17.9	20.9	23.9	dB
49	VCA gain 1	S7, S18-c, S23		1.0			4.8	8.3	11.8	dB
50	VCA gain 2	S7, S18-c, S23		-1.0	▶		-12.1	-8.6	-5.1	dB
51	Frequency response 1	S7, S18-c			250kHz 107mVp-p		-3.0	—	—	dB
52	Frequency response 2	S7			20kHz 107mVp-p		-3.0	—	—	dB
53	Voltage gain 3	S7, S16, S18-c			1kHz 20mVp-p		10.0	13.0	16.0	dB
54	Voltage gain 4	S6, S16, S18-c					10.0	13.0	16.0	dB
55	VCA gain 3	S7, S16, S18-c, S23		1.0			4.9	8.4	11.9	dB
56	VCA gain 4	S7, S16, S18-c, S23		-1.0	▶		-12.2	-8.7	-5.2	dB
57	Bias characteristics 1	S10, S18-c	1.0				-890.0	-780.0	-670.0	mV
58	Bias characteristics 2	S10, S18-c	-1.0				670.0	780.0	890.0	mV
59	Output voltage High	S7, S18-c			1.9V DC		1550.0	1660.0	—	mV
60	Output voltage Low	S7, S18-c			-1.9V DC	▶	—	-1760.0	-1650.0	mV
61	Voltage gain 1	S8			1kHz 700mVp-p	12	-3.6	-0.6	2.4	dB
62	Voltage gain 2	S8				13	-3.6	-0.6	2.4	dB
63	VCA gain 1	S8, S24		1.0		12	GALV1 (TS) – GAL1	8.0	11.5	dB
64	VCA gain 2	S8, S24		-1.0	▶	▶	GALV2 (TS) – GAL1	-8.4	-4.9	dB
65	Frequency response 1	S8			30kHz 700mVp-p	12	FAL1 (TS) – GAL1	-2.0	—	dB
66	Frequency response 2	S8			▶	13	FAL2 (TS) – GAL3	-2.0	—	dB
67	Voltage gain 3	S8, S16			1kHz 156mVp-p	12	GAL3 (TS) – GAL1	10.0	13.0	dB
68	Voltage gain 4	S8, S16				13	GAL4 (TS) – GAL3	10.0	13.0	dB
69	VCA gain 3	S8, S16, S24		1.0		12	GALV3 (TS) – GAL3 (TS)	4.5	8.0	dB
70	VCA gain 4	S8, S16, S24		-1.0	▶	▶	GALV4 (TS) – GAL3 (TS)	-11.9	-8.4	dB

(Ta = 25°C, Vcc = 1.9V, GND = VC, VEE = -1.9V)

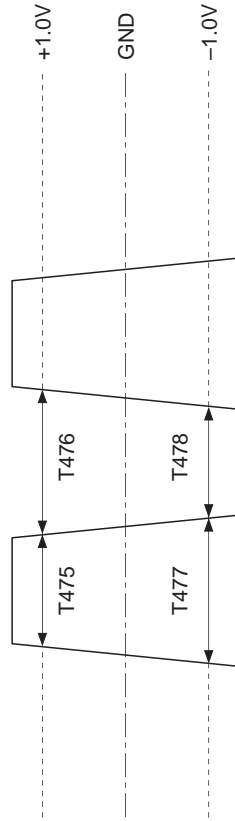
No.	Measurement item		SW conditions	Bias conditions (V)		Input	Output *IC pin No.	Ratings			
				E1	E2			Min.	Typ.	Max.	Unit
71	AL	Output voltage High 1	S8			1.9V DC	12	1580.0	1690.0	—	mV
72		Output voltage Low 1	S8			-1.9V DC	→	—	-1680.0	-1540.0	mV
73		Output voltage High 2	S8			1.9V DC	13	—	-1720.0	-1580.0	mV
74		Output voltage Low 2	S8			-1.9V DC	→	1570.0	1690.0	—	mV
75	CF	Voltage gain	S9			1kHz 260mVp-p	16	17.0	20.0	23.0	dB
76		Frequency response	S9			30kHz 260mVp-p		FCE (TS) - GCE	-3.0	—	dB
77		Output voltage High	S9			1.9V DC		1680.0	1790.0	—	mV
78		Output voltage Low	S9			-1.9V DC	→	—	-1580.0	-1090.0	mV
79	APC	Input voltage	S1			adjust input voltage	1	-1780.0	-1730.0	-1680.0	mV
80		Output voltage 1	S1			VAPCIN + 100mV		1650.0	1760.0	1870.0	mV
81		Output voltage 2	S1			VAPCIN - 100mV		-1180.0	-1070.0	-960.0	mV
82		Output voltage 3	S1, S20-c			VAPCIN	→	1700.0	1800.0	—	mV
83	EQ	Voltage gain 1	S29			1kHz 45mVp-p	29	16.5	19.0	21.5	dB
84		Voltage gain 2	S29			→	30	15.6	18.1	20.6	dB
85		Output voltage High 1	S29			1.9V DC	29	240.0	560.0	880.0	mV
86		Output voltage Low 1	S29			-1.9V DC	→	-1410.0	-1130.0	-890.0	mV
87	AGC	Output voltage High 2	S29			1.9V DC	30	590.0	840.0	1090.0	mV
88		Output voltage Low 2	S29			-1.9V DC	→	-1210.0	-880.0	-590.0	mV
89		Voltage gain 1	S2, S3, S4, S5			100kHz 40mVp-p	29	19.0	22.0	25.0	dB
90		Voltage gain 2	S2, S3, S4, S5, S17, S25			→		26.5	29.5	32.5	dB
91	AGC	Voltage gain 3	S2, S3, S4, S5, S17, S25			100kHz 100mVp-p		18.0	21.0	24.0	dB
92		Voltage gain 4	S2, S3, S4, S5, S25			→		11.5	14.5	17.5	dB

(Ta = 25°C, Vcc = 1.9V, GND = VC, VEE = -1.9V)

No.	Measurement item	SW conditions	Bias conditions (V)		Input	Output *IC pin No.	Ratings			
			E1	E2			Min.	Typ.	Max.	Unit
93	Bias characteristics 1	S12, S21-b	1.0			25	1600.0	1710.0	—	mV
94	Bias characteristics 2	S12, S21-b	-1.0				—	-1585.0	-1475.0	mV
95	MIRR frequency response 1	S2, S3, S4, S5, S12, S21-b	0.1		30kHz 100mVp-p		10.0	16.0	22.0	µs
96	MIRR frequency response 2	S2, S3, S4, S5, S12, S21-b	0.1				11.3	17.3	23.3	µs
97	MIRR frequency response 3	S2, S3, S4, S5, S12, S21-b	0.1				10.6	16.6	22.6	µs
98	MIRR frequency response 4	S2, S3, S4, S5, S12, S21-b	0.1				10.7	16.7	22.7	µs

See the figure below.

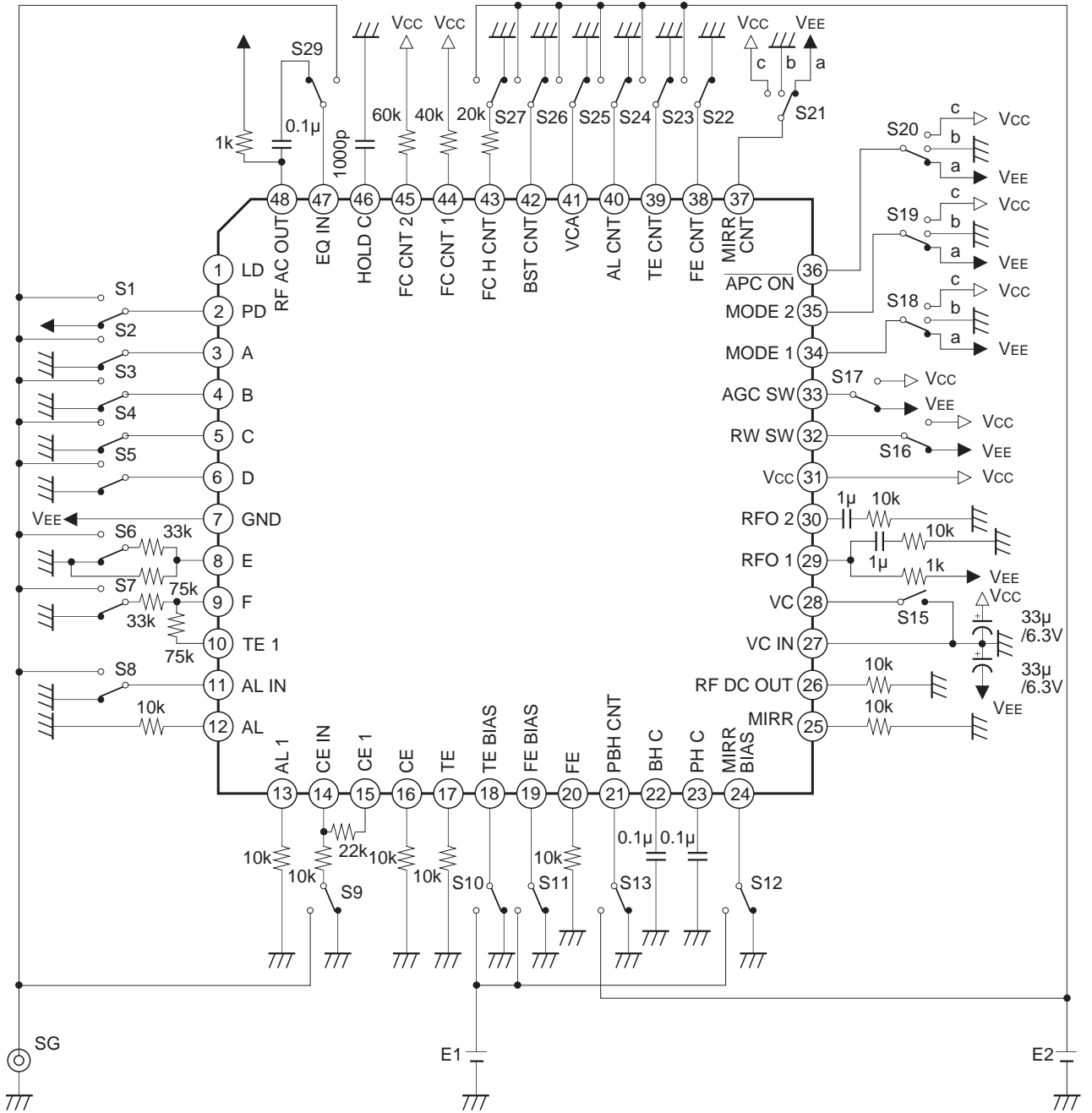
**MIRR frequency response measurement (T475 to T478)**



\* T475 measurement value + T476 measurement value = 33.3µs.

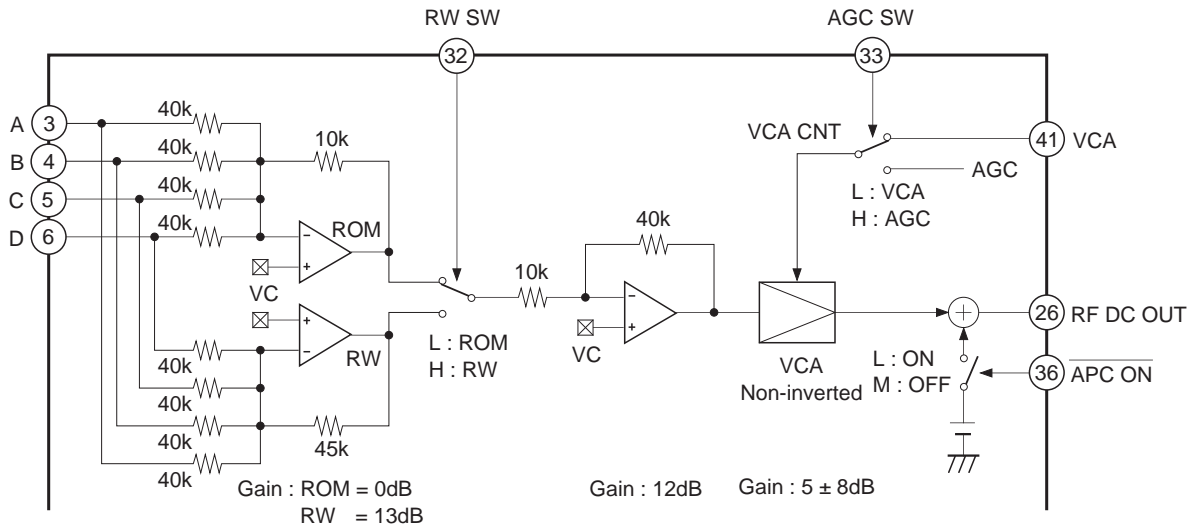
\* T477 measurement value + T478 measurement value = 33.3µs.

Electrical Characteristics Measurement Circuit



Description of Functions

RF DC



The RF DC block processes the RF DC signal that is used for the MIRR, FOK and DEFECT signals. This block supports CD-ROM/RW, and the gain can be switched by Pin 32 (RW SW). The gain during RW is 13dB higher than that during ROM. ROM is selected when Pin 32 is Low, and RW when High. This block has a VCA, and the total gain can be adjusted by Pin 41 (VCA). The VCA has the same characteristics (control voltage – gain) as the RF AC block.

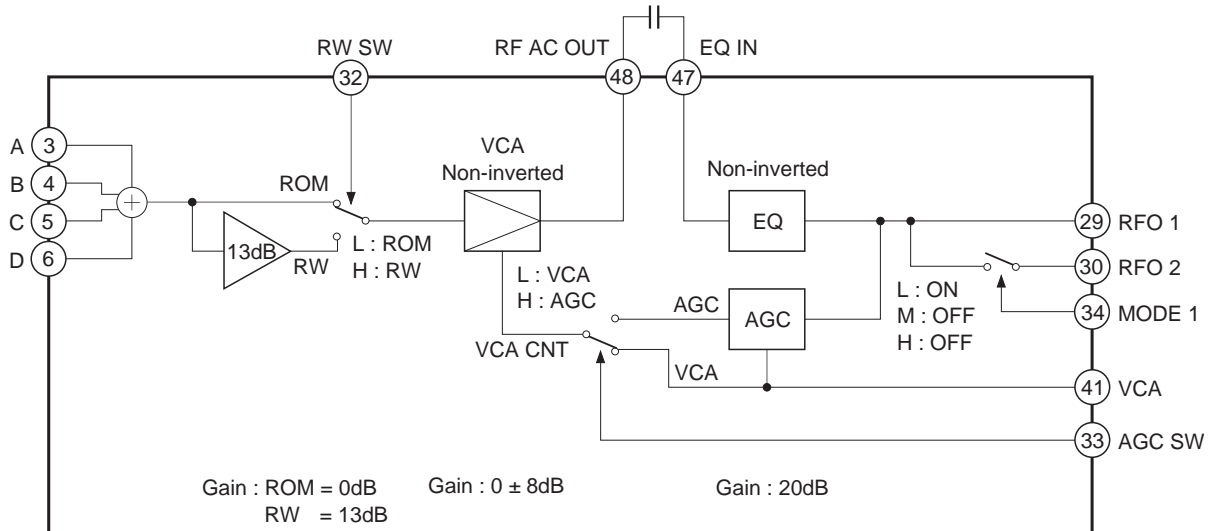
The total gain is ROM: 17 ± 8dB  
RW: 30 ± 8dB

This block has a function for shifting the output DC voltage, and this function is switched by Pin 36 (APC ON). The DC voltage is shifted when Pin 36 is Low, and not shifted when Pin 36 is Medium. When the DC voltage is shifted, the Pin 26 DC voltage equal to (Vcc-GND)/6 is shifted to the GND side.

The Pin 26 gain is as follows.

$$RF\ DC\ OUT = G_{RF\ DC} \cdot (A + B + C + D)$$

RF AC



The RF AC block processes the RF AC signal.

This block supports CD-ROM/RW, and the gain can be switched by Pin 32 (RW SW).

The gain during RW is 13dB higher than that during ROM.

ROM is selected when Pin 32 is Low, and RW when High.

This block has a VCA, and the total gain can be adjusted by the Pin 41 (VCA) voltage.

The VCA has the same characteristics (control voltage – gain) as the RF DC block.

The total gain is ROM: 20 ± 8dB  
RW: 33 ± 8dB

The capacitor values connected between this IC and the DSP can be switched , by using the Pin 30 (RFO 2) output.

The Pin 29 and 30 gains are as follows.

$$RFO\ 1 = G_{RF\ AC} \cdot (A + B + C + D)$$

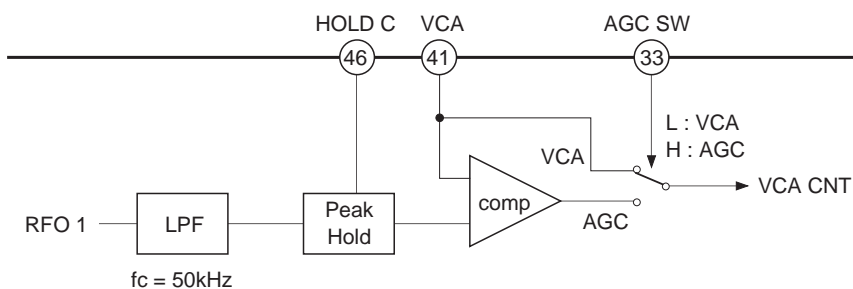
$$RFO\ 2 = G_{RF\ AC} \cdot (A + B + C + D)$$



**Pin Settings and Cut-off Frequency**

MODE 1 (Pin 34)	MODE 2 (Pin 35)	FC H CNT (Pin 43)	fc	mode
L	X	—	n	CLV
M	L		2n	
	M		4n	
	H		6n	
H	X	VC - 1V to VC to VC + 1V	0.5N to N to 1.5N	CAV

**AGC**



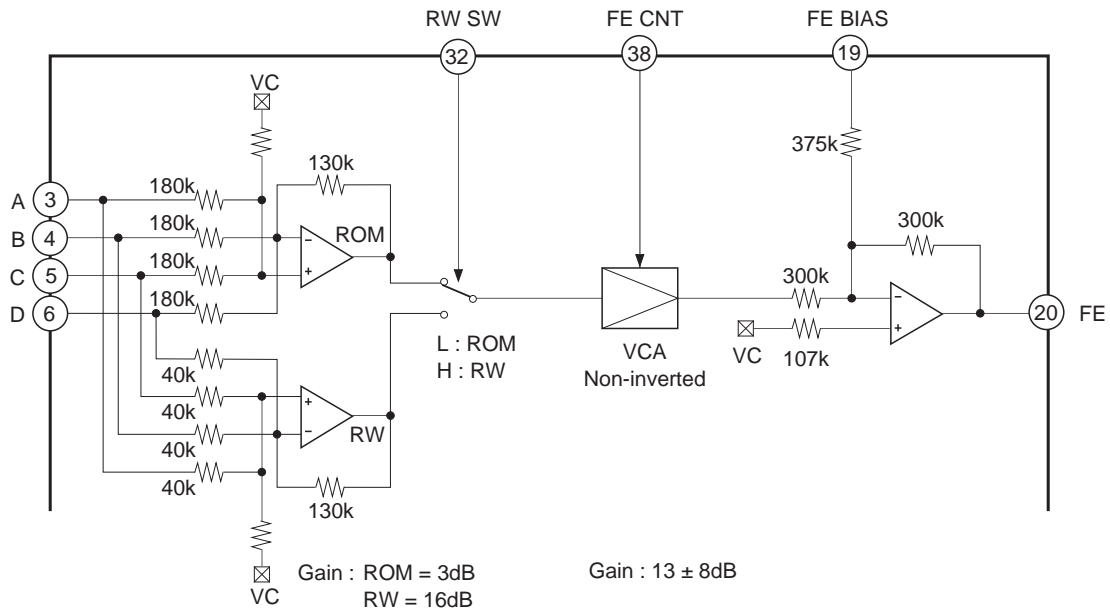
The AGC block sets the RF AC and RF DC gains.  
 AGC/VCA can be switched by Pin 33 (AGC SW).  
 VCA is selected when Pin 33 is Low, and AGC when High.

The following can be performed by the Pin 41 (VCA) voltage.

- VCA: Gain adjustment
- AGC: Output amplitude setting

Pin 46 (HOLD C) is used to connect a capacitor for setting the AGC time constant.

FE



The FE block processes the focus error signal.

This block supports CD-ROM/RW, and the gain can be switched by Pin 32 (RW SW).

The gain during RW is 13dB higher than that during ROM.

ROM is selected when Pin 32 is Low, and RW when High.

This block has a VCA, and the total gain can be adjusted by the Pin 38 (FE CNT) voltage.

The total gain is as follows.

ROM: 16 ± 8dB

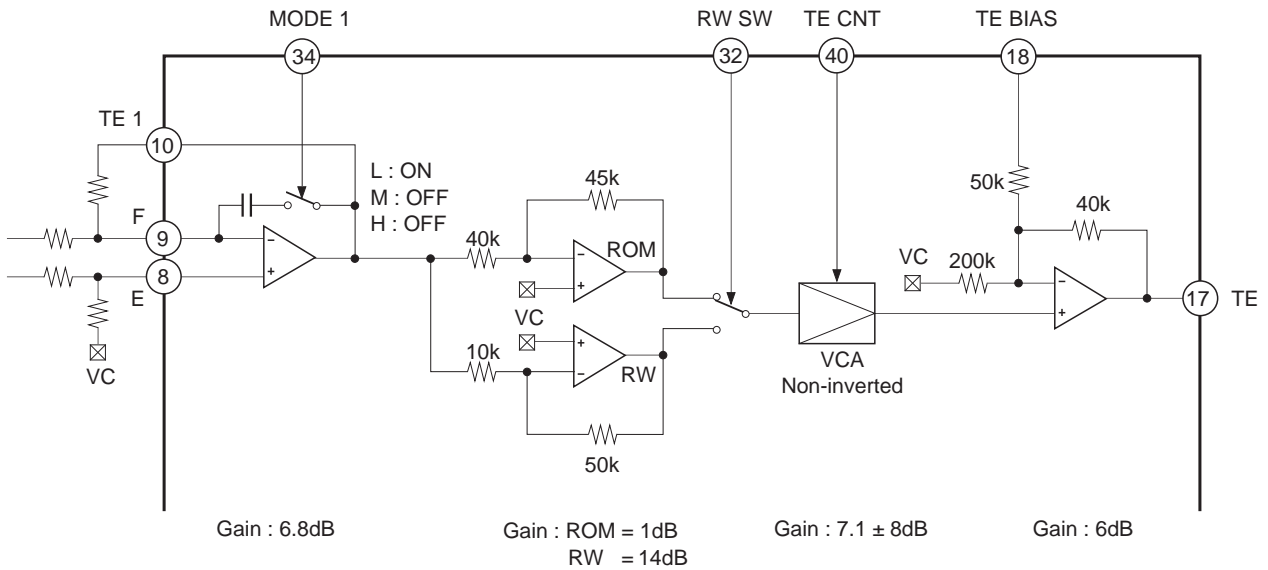
RW: 29 ± 8dB

The output DC voltage level can be adjusted by the Pin 19 (FE BIAS) voltage.

The Pin 20 gain is as follows.

$$FE = G_{FE} \cdot (B + D - A - C)$$

TE



The TE block processes the tracking error signal.

This block supports CD-ROM/RW, and the gain can be switched by Pin 32 (RW SW).

The gain during RW is 13dB higher than that during ROM.

ROM is selected when Pin 32 is Low, and RW when High.

This block has a VCA, and the total gain can be adjusted by the Pin 39 (TE CNT) voltage.

The total gain is as follows.

ROM: 20.9 ± 8dB

RW: 33.9 ± 8dB

The output DC voltage level can be adjusted by the Pin 18 (TE BIAS) voltage.

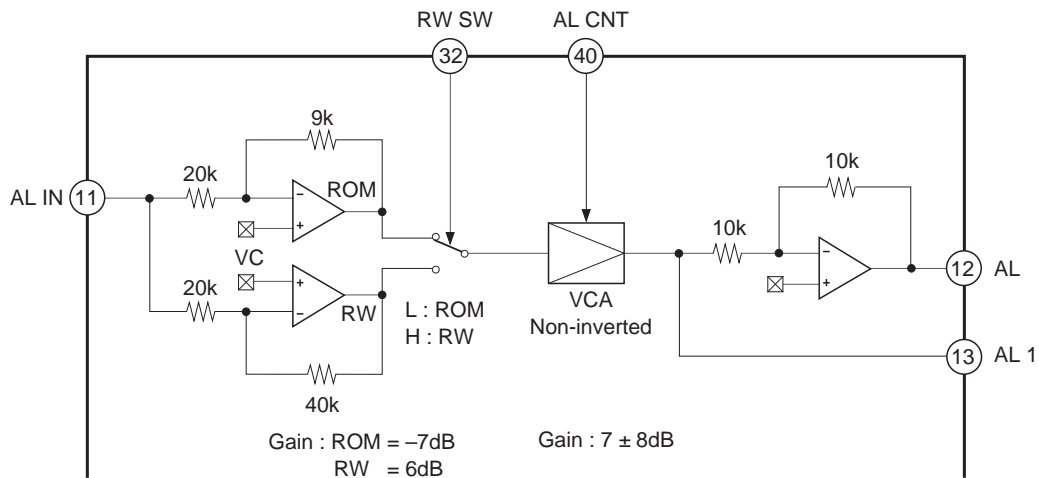
The LPF cut-off frequency can be switched by the Pin 34 (MODE 1) voltage.

fc = 20kHz when Pin 34 is Low, and fc = 250kHz when Medium or High.

The Pin 17 gain is as follows.

$$TE = G_{TE} \cdot (F - E)$$

AL



The AL block processes the alignment signal.

This block supports CD-ROM/RW, and the gain can be switched by Pin 32 (RW SW).

The gain during RW is 13dB higher than that during ROM.

ROM is selected when Pin 32 is Low, and RW when High.

This block has a VCA, and the total gain can be adjusted by the Pin 40 (AL CNT) voltage.

The total gain is as follows.

ROM: 0 ± 8dB

RW: 13 ± 8dB

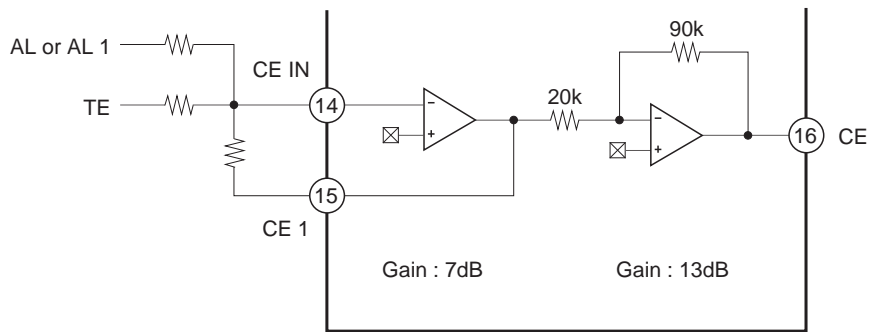
Pin 12 (AL) is the non-inverted output, and Pin 13 (AL 1) is the inverted output with respect to the input.

The Pin 12 and 13 gains are as follows.

$$AL = G_{AL} \cdot AL\ IN$$

$$AL\ 1 = -G_{AL} \cdot AL\ IN$$

**CE**



The CE block processes the center error signal.

The AL and TE signals are arithmetically amplified and output as the center error signal.

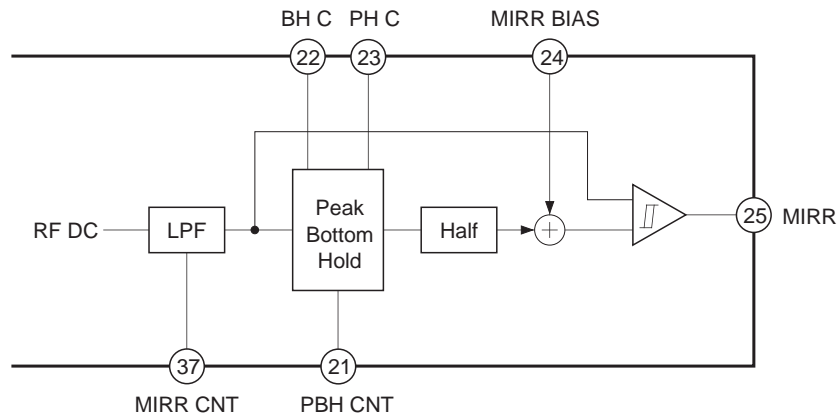
The total gain is 20dB.

The Pin 16 (CE) gain is as follows.

$$CE = G_{CE} \cdot (AL + \alpha TE): \text{straight optical path laser coupler}$$

$$CE = G_{CE} \cdot (AL 1 + \alpha TE): \text{folded optical path laser coupler}$$

**MIRR**



The MIRR block processes the MIRR signal.

The MIRR signal is generated from the RF DC signal.

The initial stage LPF is a third-order LPF, and separates the envelope and EFM signals.

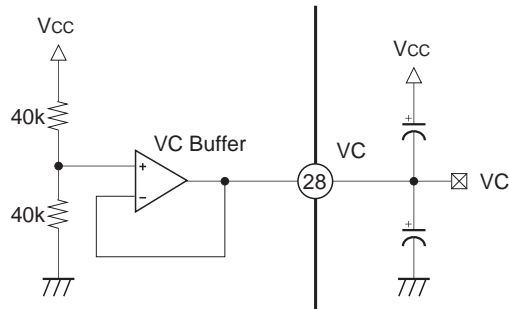
The LPF cut-off frequency can be switched by the Pin 37 (MIRR CNT) voltage.

Pins 22 (BH C) and 23 (PH C) are used to connect capacitors for peak and bottom hold of the separated envelope signal.

The peak and bottom hold time constants are set by the Pin 21 (PBH CNT) voltage.

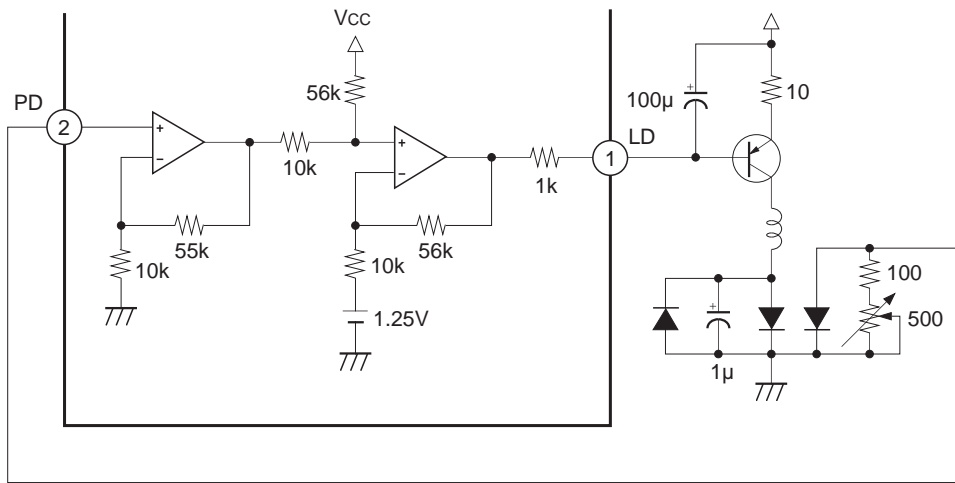
The DC voltage level of the mirror circuit can be adjusted by the Pin 24 (MIRR BIAS) voltage.

**Center Voltage Generation Circuit**



The center voltage  $VC = (V_{cc} + GND)/2$  is output from Pin 28 (VC).  
 The maximum output current is about  $\pm 3mA$ .

**APC**

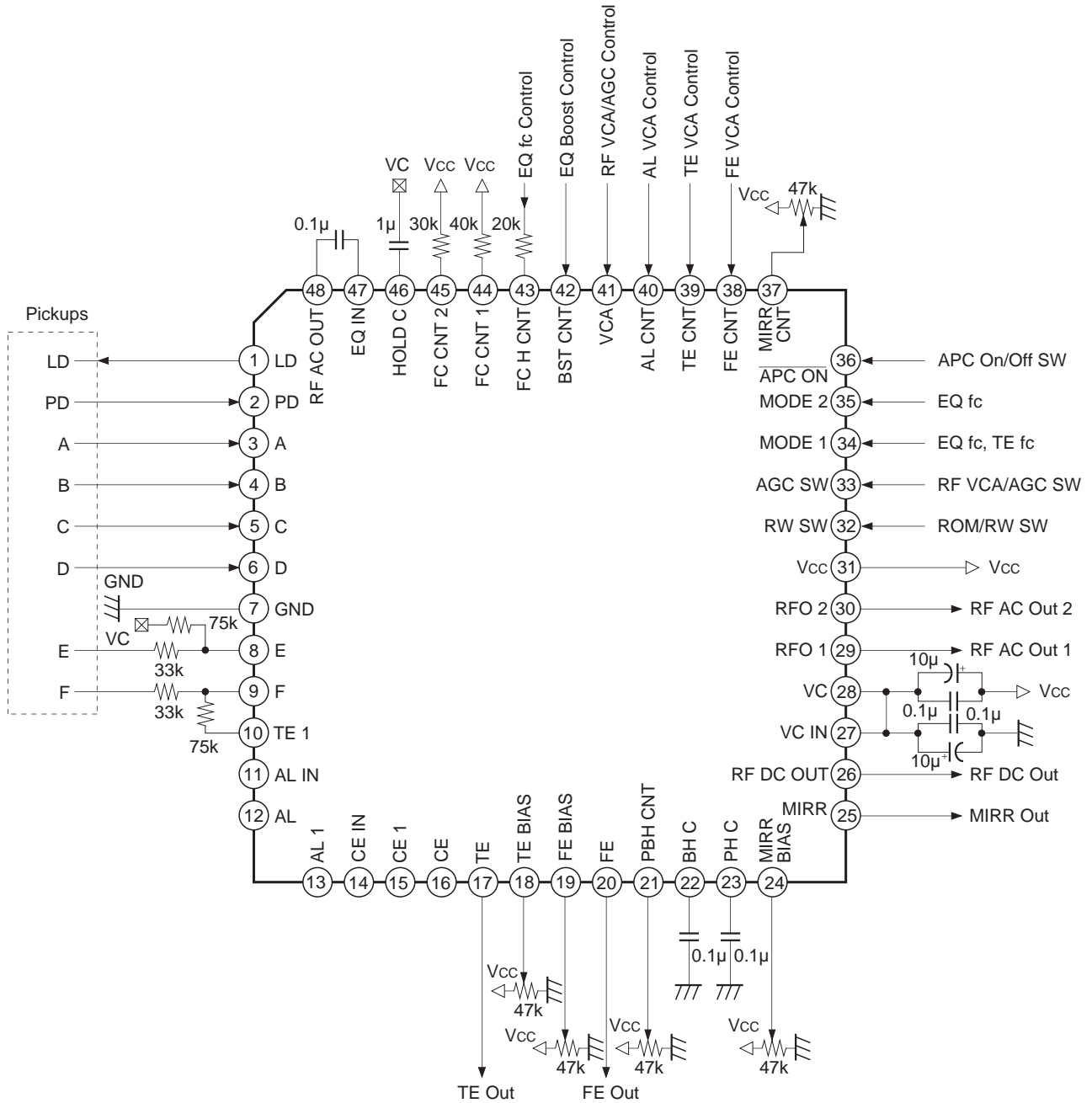


When the laser diode is driven by a constant current, the optical power output has extremely large negative temperature characteristics.

The APC circuit uses a monitor photodiode to control the laser diode current in order to maintain the optical power output at a constant level.

Application Circuit

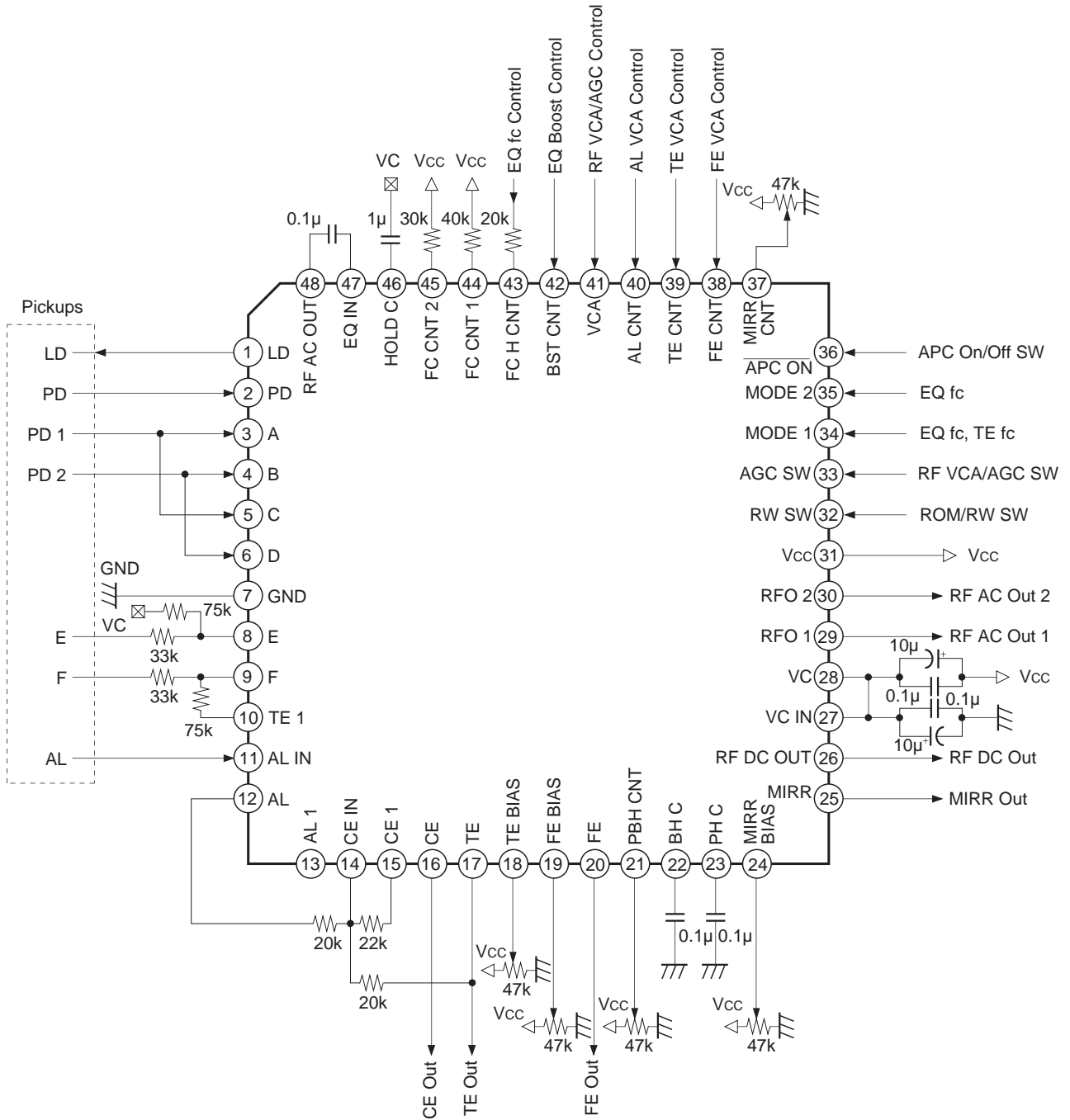
3 spots



Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

Application Circuit

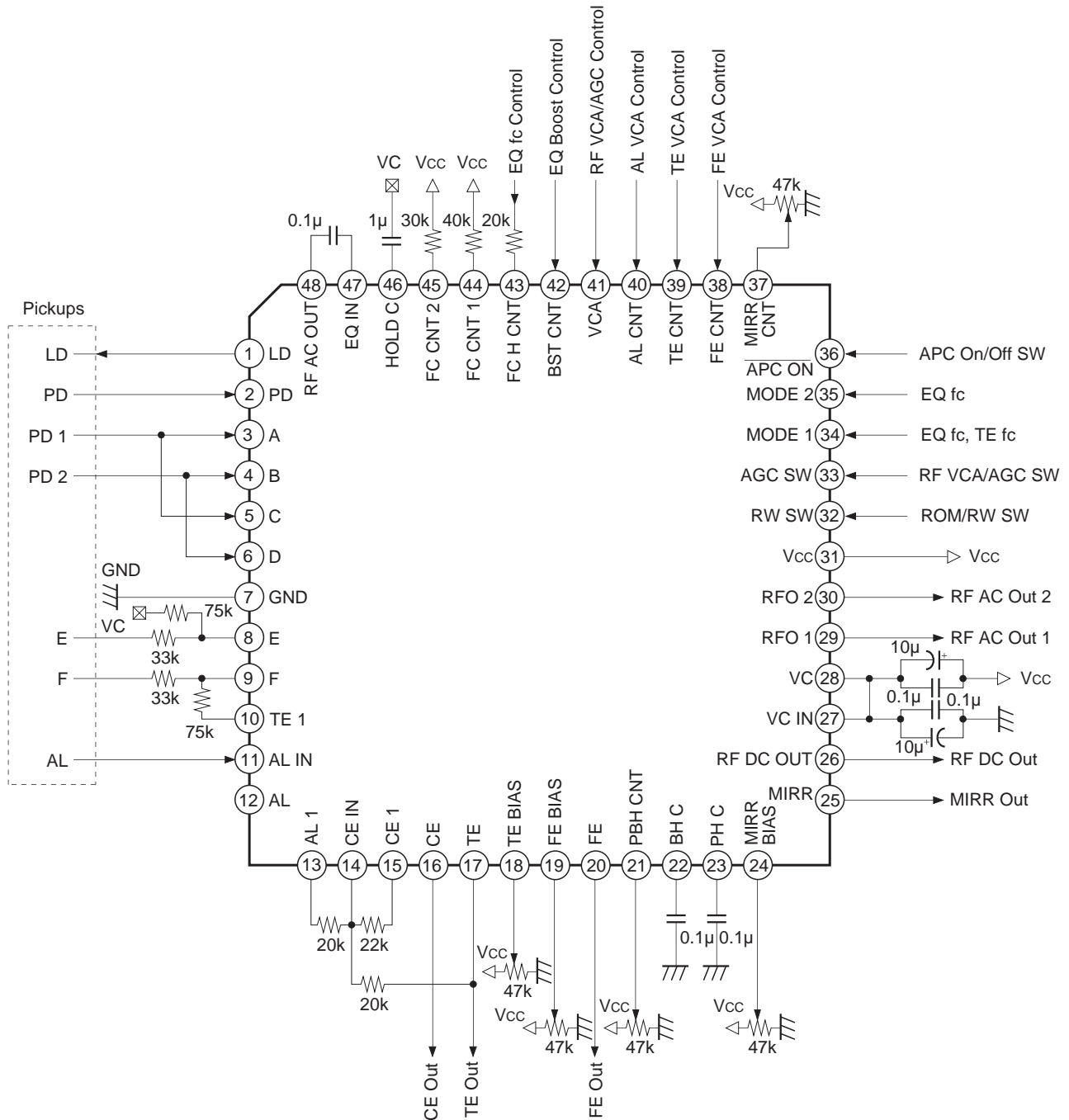
Laser coupler (straight optical path type)



Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

Application Circuit

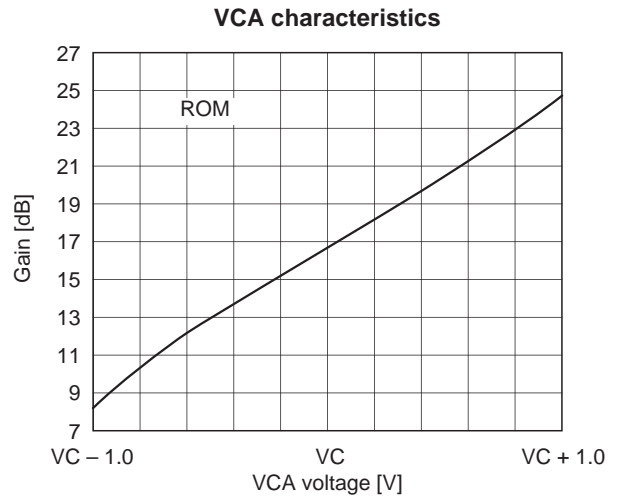
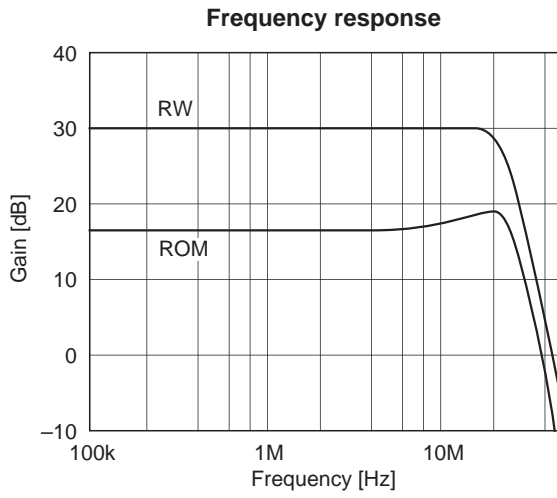
Laser coupler (folded optical path type)



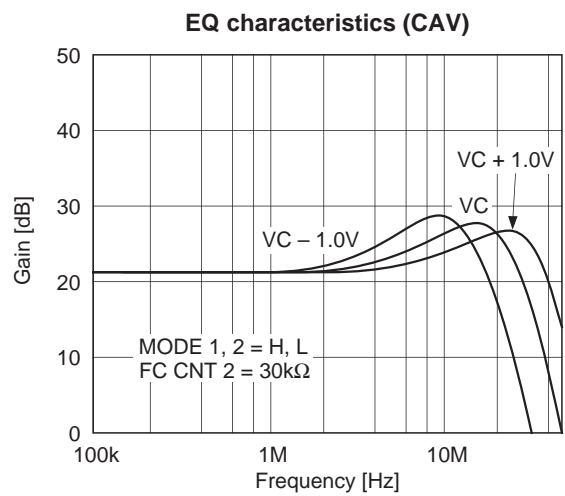
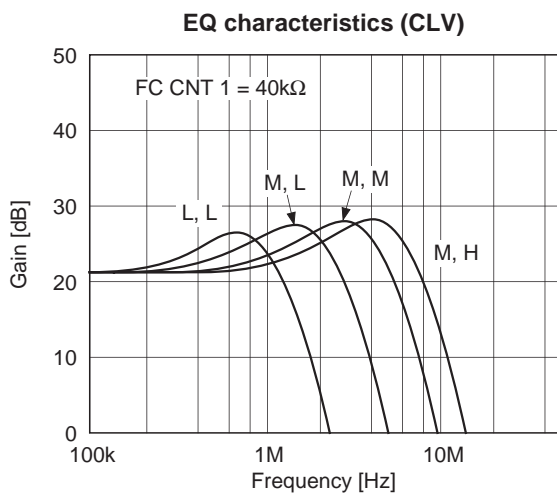
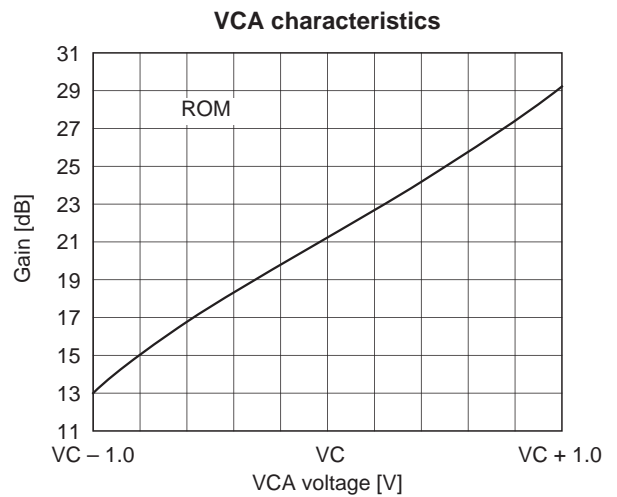
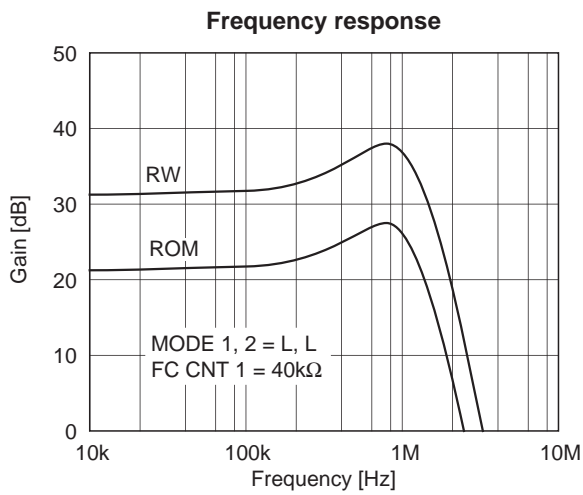
Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

Example of Representative Characteristics (VC voltage reference)

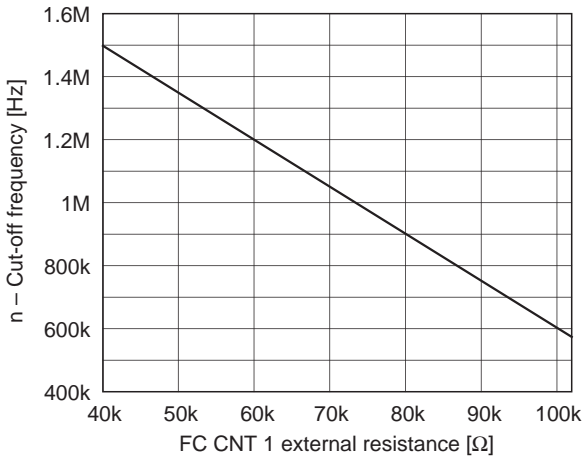
RF DC Characteristics Graphs (Pin 26)



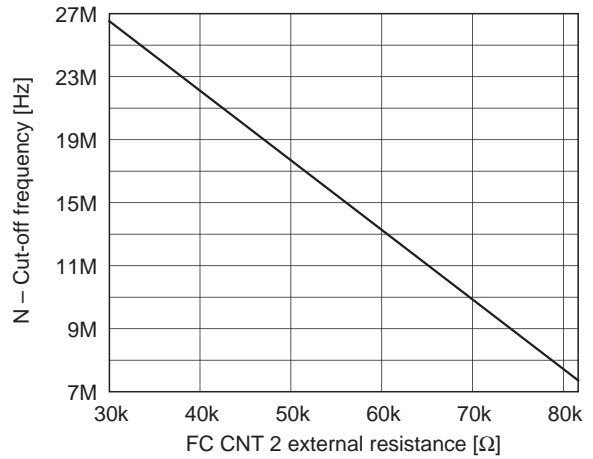
RF AC Characteristics Graphs (Pin 29)



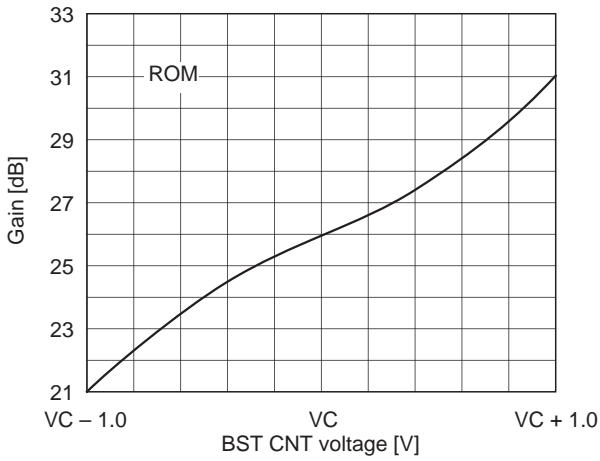
**Cut-off frequency response 1**



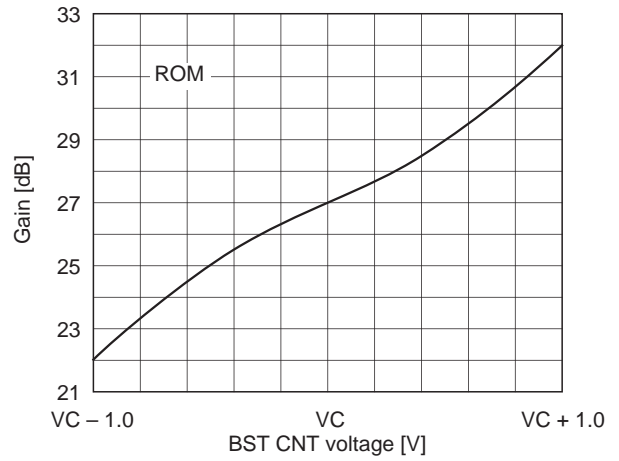
**Cut-off frequency response 2**



**Boost characteristics (CLV)**

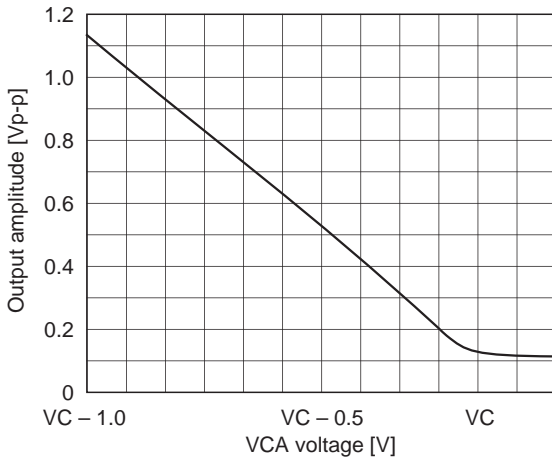


**Boost characteristics (CAV)**



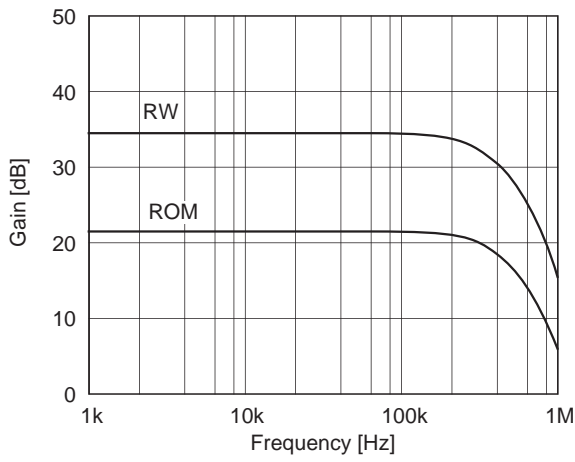
**AGC Characteristics Graph (Pin 29)**

**Output amplitude characteristics**

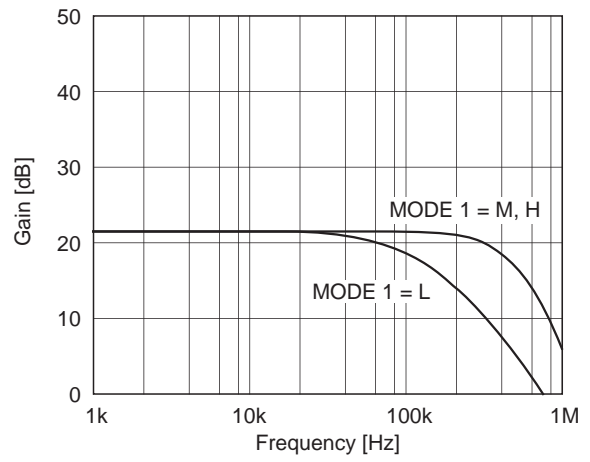


TE Characteristics Graphs (Pin 17)

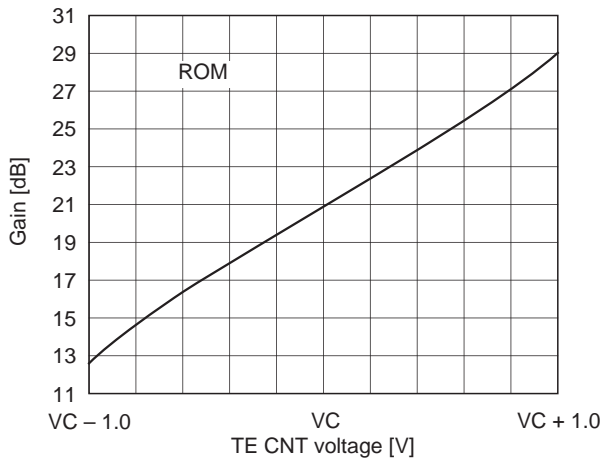
Frequency response 1



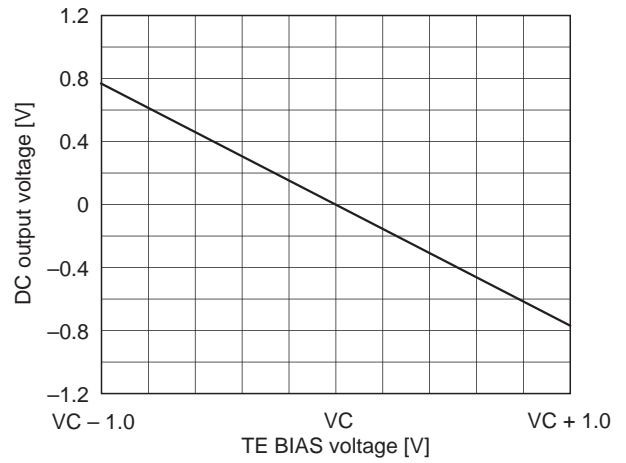
Frequency response 2



TE CNT characteristics



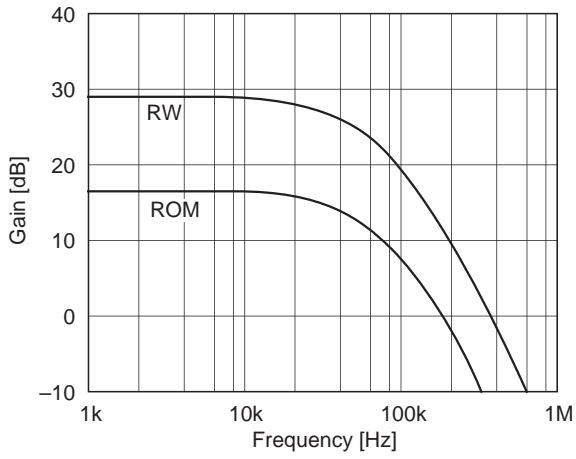
TE BIAS characteristics



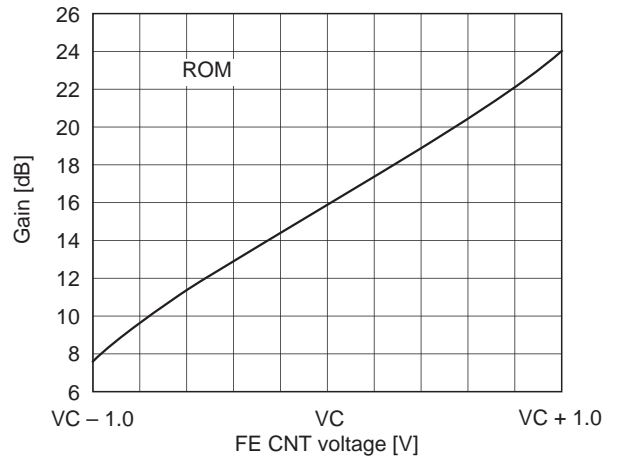
\* TE BIAS voltage; DC output voltage is 0V at VC.

FE Characteristics Graphs (Pin 20)

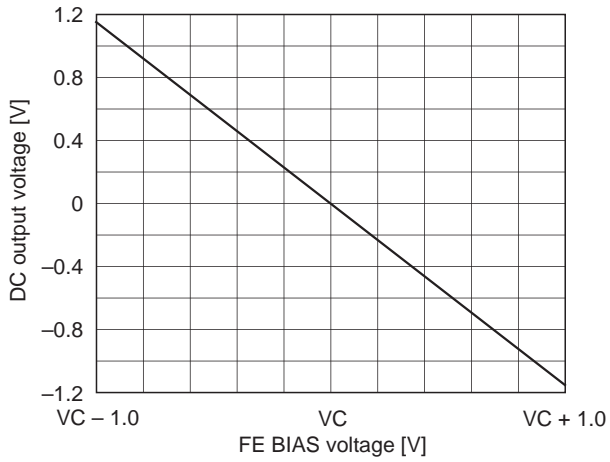
Frequency response



FE CNT characteristics



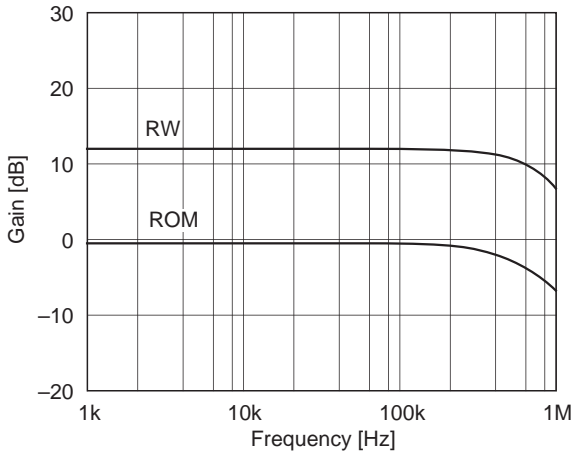
FE BIAS characteristics



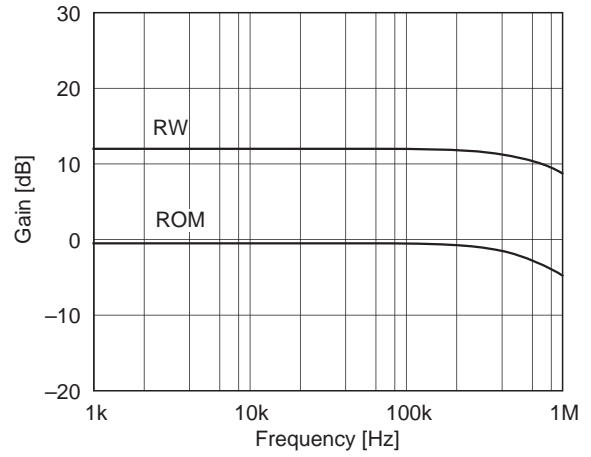
\* FE BIAS voltage; DC output voltage is 0V at VC.

**AL Characteristics Graphs (Pins 12 and 13)**

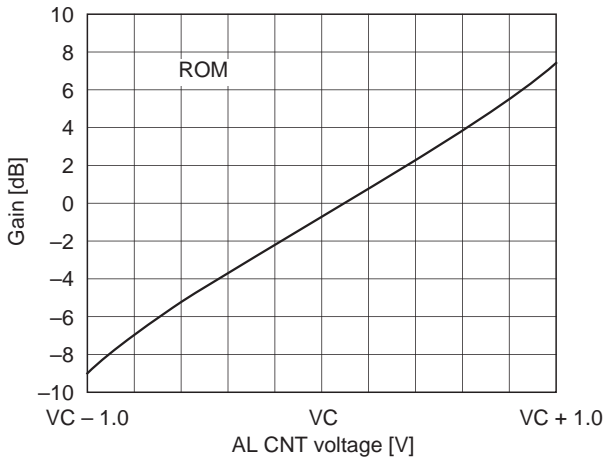
**Frequency response (AL)**



**Frequency response (AL 1)**

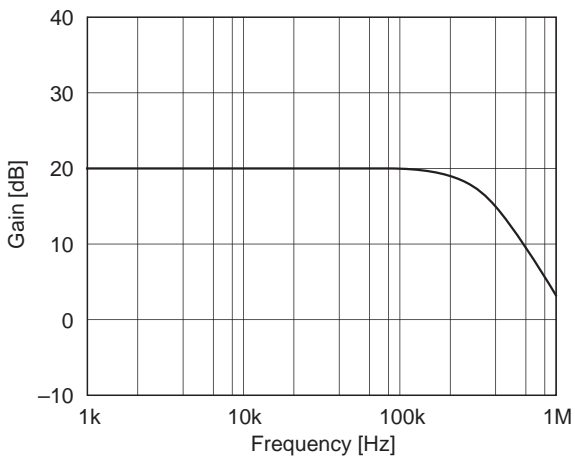


**AL CNT characteristics**



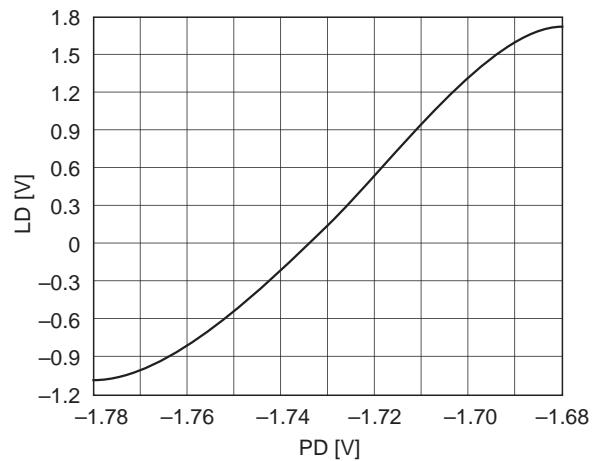
**CE Characteristics Graph (Pin 16)**

**Frequency response**



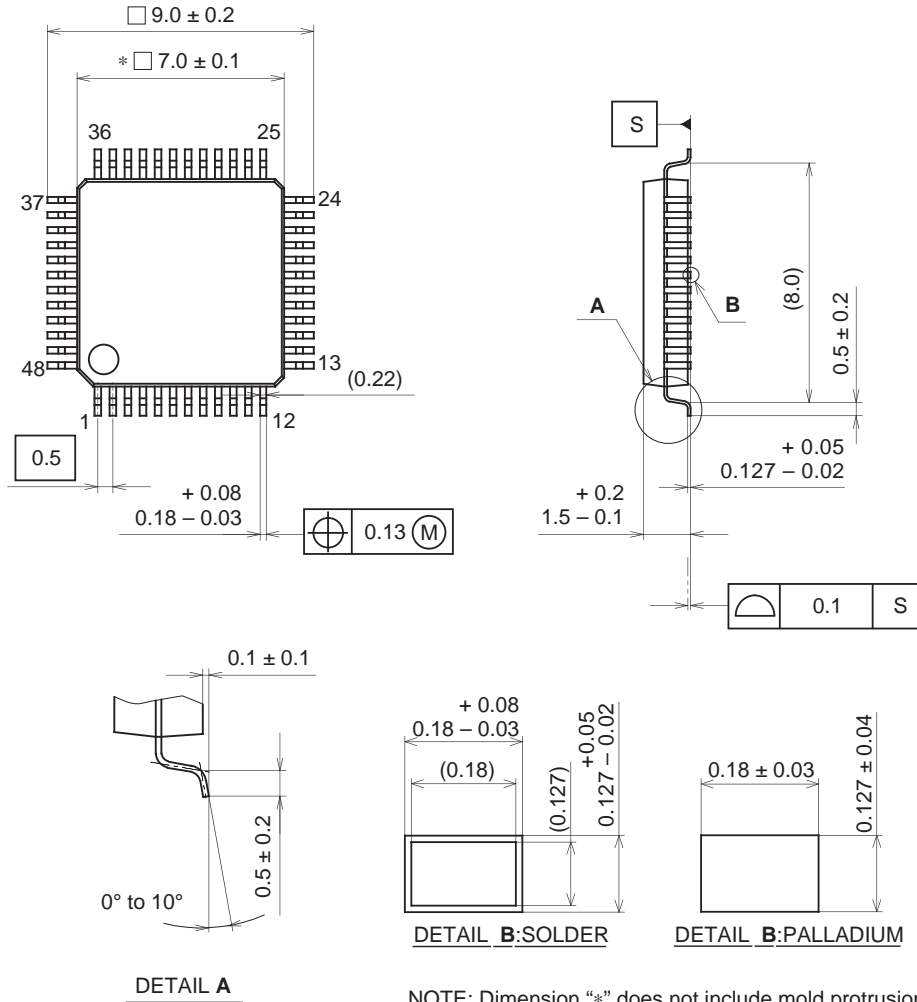
**APC Characteristics Graph (Pin 1)**

**LD voltage vs. PD voltage**



Package Outline Unit: mm

48PIN LQFP (PLASTIC)



NOTE: Dimension "\*" does not include mold protrusion.

PACKAGE STRUCTURE

SONY CODE	LQFP-48P-L01
EIAJ CODE	LQFP048-P-0707
JEDEC CODE	_____

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER/PALLADIUM PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	0.2g



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